

REV	LOCATIONS	DESCRIPTION	DATE	REVISER	APPD
1		Corrected the terminal material	28/NOV/23	KATE	LEO

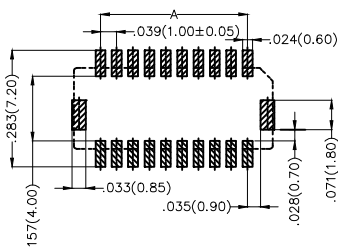
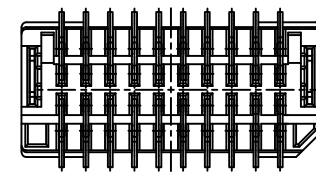
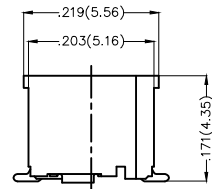
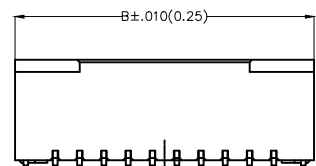
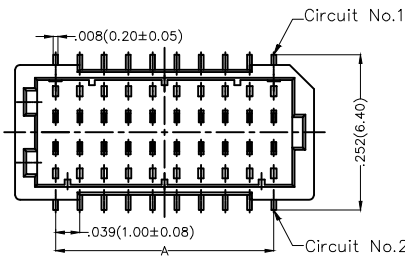
Electrical
Current Rating:1A AC(rms)/DC(AWG32)
Voltage Rating: 50V AC(rms)/DC
Contact Resistance: 20 m Ω Max
Insulation Resistance:100 M Ω MIN
Withstanding Voltage:500V AC r.m.s
Temperature Range-Operating: -25°C~+85°C
Material and Plating
Housing:PA9T(UL 94V-0)
 Contact Pin:Phosphor bronze/ Gold plated
Solder Tab:Copper alloy/ Tin plated

Circuits (n)	Part No.	Dimensions(in/mm)	
		A	B
10	FWF10003-D10S14W5M	.157(4.00)	.287(7.30)
12	FWF10003-D12S14W5M	.276(5.00)	.406(8.30)
16	FWF10003-D16S14W5M	.276(7.00)	.406(10.30)
20	FWF10003-D20S14W5M	.354(9.00)	.484(12.30)
30	FWF10003-D30S14W5M	.551(14.00)	.681(17.30)
40	FWF10003-D40S14W5M	.748(19.00)	.878(22.30)
50	FWF10003-D50S14W5M	.945(24.00)	1.075(27.30)

Ordering Information

FWF 100 03 — D XX S 1 4 W5 M
1 2 3 4 5 6 7 8 9 10

1	Category FWF-Wafer	2	Series Number 100-Pitch1.0mm	3	Distinction No. 03	4	Row Option D-Double Row	5	Circuits XX	6	Entry Angle S-180° Vertical
7	Plating 1-Gold Plated	8	Material-Resin 4-PA9T	9	Color-Resin W5-White	10	Packaging M-Reel				



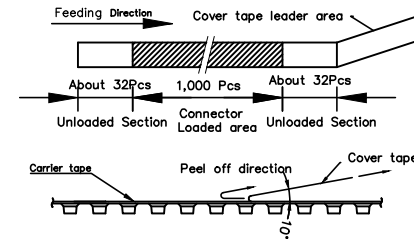
Recommended P.C.Board Layout

 THIRD ANGLE PROJECTION		GENERAL TOLERANCES (UNLESS SPECIFIED)		APPROVE BY FRANK	DATE 28/JUN/13	PART NO. FWF10003-DXXS14W5M	ITEM NO. FWF10003	 Leader Of Industry		
		X.±.012(0.30)	X'.±5°	CHECKED BY	DATE	TITLE Wire to Board (Wafer) Pitch 1.0mm 180° Vertical (SMT)				
DESIGN UNITS Inch (metric)		X.X±.008(0.20)	X'±2°	JACOB	28/JUN/13	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO TXGA INDUSTRIAL ELECTRONICS(S.Z)CO.,LTD AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			REV 1	SHEET NO. 1/2
		X.XX±.006(0.15)	.XX'±1°	DRAWN BY	DATE					
SCALE 5:1	SIZE A4	X.XXX±.004(0.10)	.XXX'±0.5°	CHERRY	28/JUN/13					

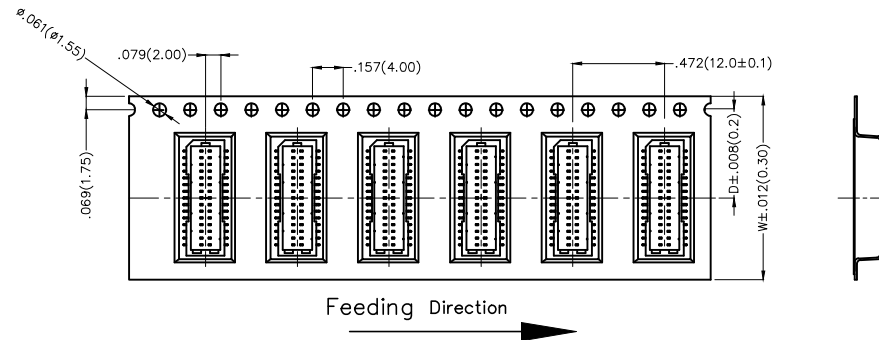
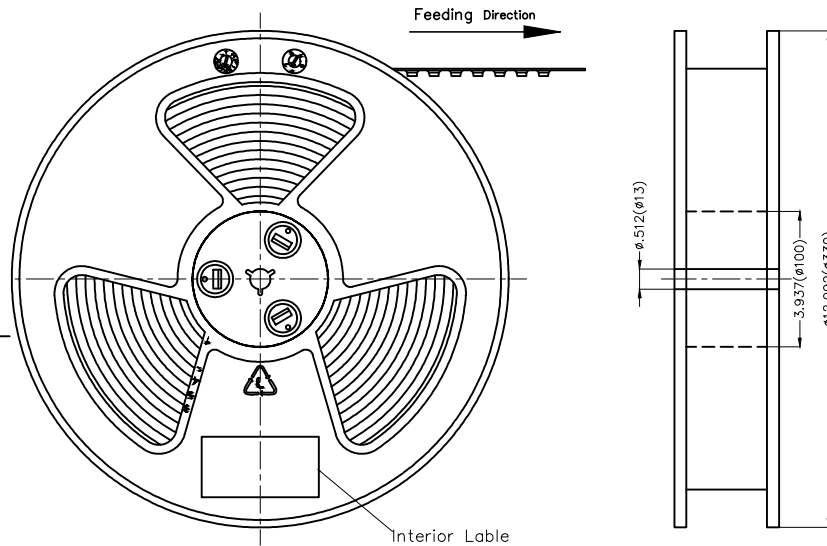
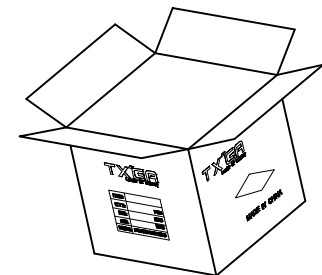
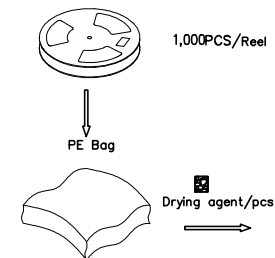
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Note:

1. 10 sprocket hole cumulative tolerance ± 0.2
2. Carrier camber is within 1.0mm in 250mm
3. Materlat: White Conductive polystyrene Alloy 100% recyclable
4. All dimensions meet EIA-481-3 requirements
5. Peel off force of cover tape&carrier tape: 20g~130g(0.2N~1.3N)
6. Component load per 13" reel: 1,000 pcs



Circuits (n)	Dimensions(in/mm)	
	D	W
10	.453(11.50)	.945(24.00)
12	.453(11.50)	.945(24.00)
16	.453(11.50)	.945(24.00)
20	.453(11.50)	.945(24.00)
30	.453(11.50)	.945(24.00)
40	.798(20.20)	1.732(44.00)
50	.798(20.20)	1.732(44.00)



 THIRD ANGLE PROJECTION		GENERAL TOLERANCES (UNLESS SPECIFIED)		APPROVE BY FRANK	DATE 28/JUN/13	PART NO. FWF10003-DXXS14W5M	ITEM NO. FWF10003	 Leader Of Industry	
		X.±.012(0.30)	X.±5°	CHECKED BY	DATE	TITLE			
DESIGN UNITS Inch (metric)		X.X±.008(0.20)	X.±2°	JACOB	28/JUN/13	Wire to Board (Wafer) Pitch 1.0mm 180° Vertical (SMT)		REV 1	SHEET NO. 2/2
		X.XX±.006(0.15)	.XX'±1"	DRAWN BY	DATE	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO TXGA INDUSTRIAL ELECTRONICS(S.Z)CO.,LTD AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			
SCALE 5:1	SIZE A4	X.XXX±.004(0.10)	.XXX±0.5°	CHERRY	28/JUN/13				